


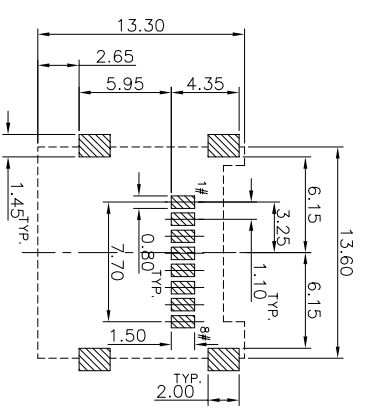
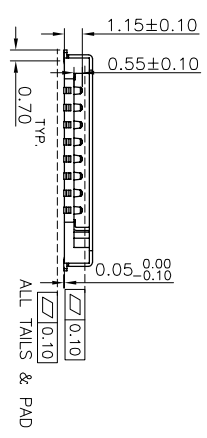
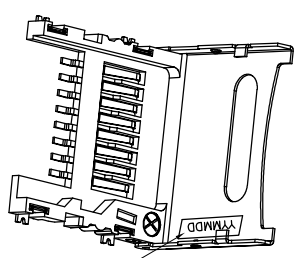
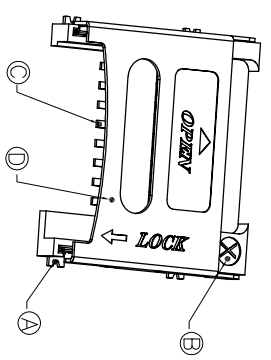
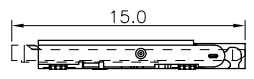
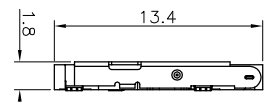
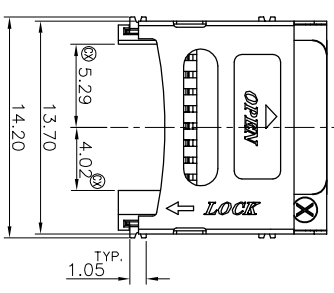


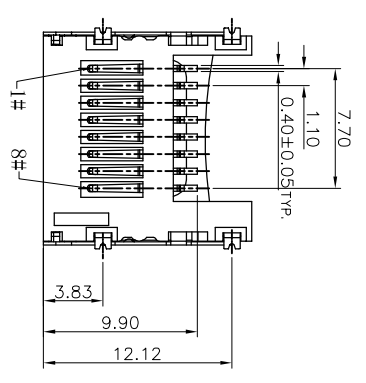
REV.	EGN NO.	OR DESCRIPTION	REVISED	DATE
A		S080522-3A	MARK	2008.10.15

SPECIFICATIONS:
 1. MATERIAL: HOUSING:HIGH TEMPERATURE THERMOPLASTIC. UL94V-0,BLACK
 SHELL:STAINLESS STEEL.
 CONTACT:COPPER ALLOY.
 SOLDER PAD: COPPER ALLOY.
 2. PLATING:
 CONTACT: GOLD FLASH PLATED OVER,
 50u" Min. Ni .
 SOLDER PAD:100u" Min. Sn PLATING OVER
 50u"Min. Ni .
 3.ELECTRICAL CHARACTERISTIC:
 CONNECT RESISTANCE:80 MEGOHMS/PRE PIN Max.
 INSULATION RESISTANCE:1000 MEGAOHMS Min.
 VOLTAGE WITHSTAND:500V AC for 1 minute
 4.TO CONFORM TO SINGATRON HARADOUS SUBSTANCE FREE SPEC.
 5.HALOGEN FREE PRODUCT IDENTIFICATI MARK ON JACK: 
 6.HALOGEN FREE PRODUCT IDENTIFICATION LOGO ON PACKING: 
 7.DATE CODE: 


SHELL LOCK



RECOMMENDED PCB PATTERN LAYOUT
 TOLERANCE: ±0.05



Pin No.	Name	Type	DESCRIPTION
1	DATA2	I/O/PP	Data Line [bit2]
2	CD/DAT3	I/O/PP	Card Detect Data Line [bit3]
3	CMD	PP	Command Response
4	VDD	S	Supply Voltage
5	CLK	I	Clock
6	VSS	S	Supply Voltage Ground
7	DAT0	I/O/PP	Data Line [bit0]
8	DAT1	I/O/PP	Data Line [bit1]

	D	C	B	A	NO
Shell	1	8	1	4	
Contact	1	8	1	4	
Housing	1	8	1	4	
Solder Pad	1	8	1	4	
DESCRIPTION	STAINLESS STEEL.	COPPER ALLOY.	HIGH TEMPERATURE THERMOPLASTIC. UL94V-0.	COPPER ALLOY.	
MATERIAL					Sn:100u"min Ni:50u"min
PLATING & COLOR	/	Gold Flash	BLACK		
TITLE	T-FLASH CARD CONNECTOR				
 Singatron Enterprise Co., Ltd. 信音企業股份有限公司					
MARKING: 2008.10.15 SANDY 2008.10.15 MAX 2008.10.15 SCALE 1:1 SIZE: A3 SHEET: 10/1 REV: A CUSTOMER COPY					

